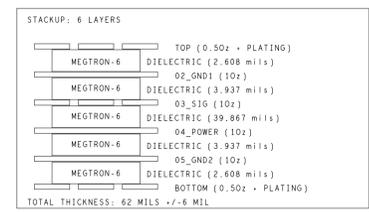


NOTES (UNLESS OTHERWISE SPECIFIED):

REVISIONS				
ZONE	REV	DESCRIPTION	DATE	APPROVED
A		ORIGINAL RELEASE	XX-XX-XX	X.X.

IMPEDANCE DETAILS: IMPEDANCE TOLERANCE: +/- 10%

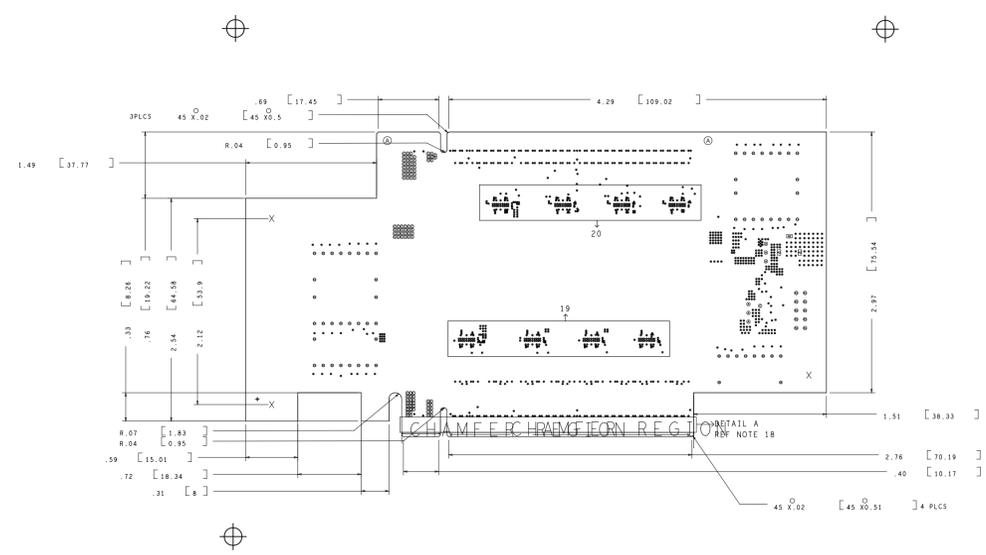
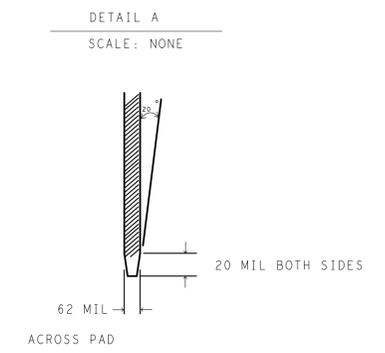
LAYERS	50 OHM		100 OHM	
	WIDTH	SPACING	WIDTH	SPACING
TOP-COATED	4.5 MIL	-	-	-
TOP-UNCOATED	-	4.8 MIL	8.7 MIL	-
SIG1	6.4 MIL	-	-	-
BOTTOM-UNCOATED	-	4.8 MIL	8.7 MIL	-
BOTTOM-COATED	4.5 MIL	-	-	-



DRILL CHART: TOP TO BOTTOM

ALL UNITS ARE IN MILS

FIGURE	SIZE	TOLERANCE	PLATED	DTF
•	8.0	+0.0/-8.0	PLATED 826	REF NOTE 16
•	8.1	+0.0/-8.1	PLATED 243	REF NOTE 16
•	10.0	+0.0/-10.0	PLATED 96	REF NOTE 16
•	32.46	+3.0/-3.0	PLATED	60
•	40.0	+3.0/-3.0	PLATED	6
•	40.16	+3.0/-3.0	PLATED	10
□	90.55	+2.0/-2.0	NON-PLATED	2
X	125.0	+2.0/-2.0	NON-PLATED	3
□	62.99x39.37	+3.0/-3.0	PLATED	1
□	62.99x39.37	+3.0/-3.0	PLATED	2



- NOTES:
- FABRICATE BOARD PER IPC-A-6006
 - MATERIAL: MEGTRON-6, 6 LAYER BOARD.
 - BOARD THICKNESS: 62 MIL +/- 6 MIL TOL.
 - BOARD DIMENSIONS ARE IN INCH[MM].
 - ALL HOLES ARE PLATED THROUGH UNLESS OTHERWISE SPECIFIED.
 - ALL DRILLS IN DRILL CHART ARE FINISHED HOLE SIZES.
 - SOLDER MASK BOTH SIDE WITH GREEN LIQUID PHOTO IMAGABLE.
 - THIS IS A ROHS COMPLIANT BOARD.
 - SILKSCREEN BOTH SIDE "WHITE EPOXY" OVER SOLDER MASK
 - DEBURR ALL SHARP EDGES
 - BOW AND TWIST: SHOULD NOT EXCEED 0.005" PER INCH.
 - PLATED PADS ON TOP AND BOTTOM MUST BE SAME HEIGHT AS CONDUCTOR PAD AND TRACE.
 - NO VENDOR LOGO OR NAME ON THE BOARD.
 - MINIMUM PLATING IN ALL THE THROUGH HOLE SHALL BE 0.001 INCH CU.
 - CLIP THE SILKSCREEN ON NO MASK AREAS.
 - ALL 8, 8.1 AND 10 MIL DRILL NEEDS TO BE NON CONDUCTIVE VIA FILL AND PLATE OVER ON BOTH SIDE. THESE VIAS SHOULD BE FLAT AND SMOOTH ON BOTH SIDE.
 - REMOVED UNUSED PADS IN ALL INNER LAYERS.
 - PLATING IN THIS AREA NEEDS SELECTIVE HARD GOLD PLATING TO BE FLAT AND PLATED A MINIMUM OF 50 MICRO INCHES OF GOLD OVER 200 MICRO INCHES OF NICKEL. HARDNESS REQUIRED TO BE 130-200 KNOOP.
 - THE REST OF BOARD SHALL BE PLATED A MINIMUM OF 3 MICRO INCHES OF GOLD.
 - IN THIS AREA THE SURFACE PROFILE SHALL BE MAINTAINED WITHIN 2MIL ON TOP LAYER
 - IN THIS AREA THE SURFACE PROFILE SHALL BE MAINTAINED WITHIN 2MIL ON BOTTOM LAYER

ALL PARTS, MATERIALS AND FINISHED ASSEMBLY SHALL MEET THE ROHS COMMISSION DELEGATED DIRECTIVE (EU) 2015/863 OF 31 MARCH 2015 AMENDING ANNEX I TO DIRECTIVE 2011/65/EU. A CERTIFICATE OF COMPLIANCE IS REQUIRED UPON REQUEST.

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE:
DECIMALS .XX .01 .0-30°
XXX .005
RMS ALL MACHINED SURFACES. BREAK ALL SHARP EDGES AND CORNERS. REMOVE BURRS. UNDERLINED DIM. NOT TO SCALE. THIRD ANGLE ORTHOGRAPHIC PROJECTION IS USED.

PART NO. 170-47772		NXP SEMICONDUCTORS	
THIS DOCUMENT CONTAINS INFORMATION PROPRIETARY TO NXP AND SHALL NOT BE USED FOR ENGINEERING DESIGN PROCUREMENT OR MANUFACTURE IN WHOLE OR IN PART WITHOUT THE CONSENT OF NXP.		6501 WILLIAM CANNON DRIVE WEST AUSTIN, TEXAS 78735 USA	
APPROVALS	DATE	TITLE: PRINTED WIRING BOARD PCIE_ADD_IN_CARD_REV-A1	
DRAWN W. MEAD	06-21-21	SIZE	CAD FILE NAME LAY-47772
CHECKED XXXXX	06-21-21	DWG. NO.	FAB-47772
DESIGN ENGINEER XXXXX	06-21-21	REV	A
SCALE	DO NOT SCALE DRAWING	SHEET	OF